

IN THE CLAIMS

1. (Currently Amended) A hybrid substrate comprising:
a carrier substrate having a plurality of pockets patterned thereon; and
at least two substrates, each substrate being formed from a different material and being deposited within a separate pocket of the plurality of pockets such that at least a portion of the at least two substrates protrudes above the surface of the carrier substrate, for fabricating a plurality of devices; and
an oxide layer deposited upon the carrier substrate so as to fill any gaps between each of the at least two substrates and the pocket.

2. (Currently Amended) The hybrid substrate according to Claim 1, wherein the at least two substrates are different from each other ~~and are approximately co-planar with a top surface of the carrier substrate.~~

3. (Previously Presented) The hybrid substrate according to Claim 1, wherein the at least two substrates are different from each other and are bonded to the carrier substrate.

4. (Previously Presented) The hybrid substrate according to Claim 1, wherein each of the at least two different substrates are selected from the group consisting of GaAs, InP, silicon (Si), substrate materials for optoelectronic devices, and GaN-based substrate materials for high-electron mobility transistors (HEMTs).

5. (Previously Presented) The hybrid substrate according to Claim 1, wherein the carrier substrate is selected from the group consisting of AlN, quartz, glass, ceramic, CVD diamond, and sapphire.

6. (Previously Presented) The hybrid substrate according to Claim 1, wherein the carrier substrate is a high thermal conductive substrate.

7-18. (Cancelled)

19. (Previously Presented) The hybrid substrate according to Claim 1, wherein each pocket of the plurality of pockets has a greater surface area than a surface area of a cross-section of a substrate deposited within that pocket.

20. (Previously Presented) The hybrid substrate according to Claim 1, wherein the at least two substrates and the carrier substrate are each formed from a different material.